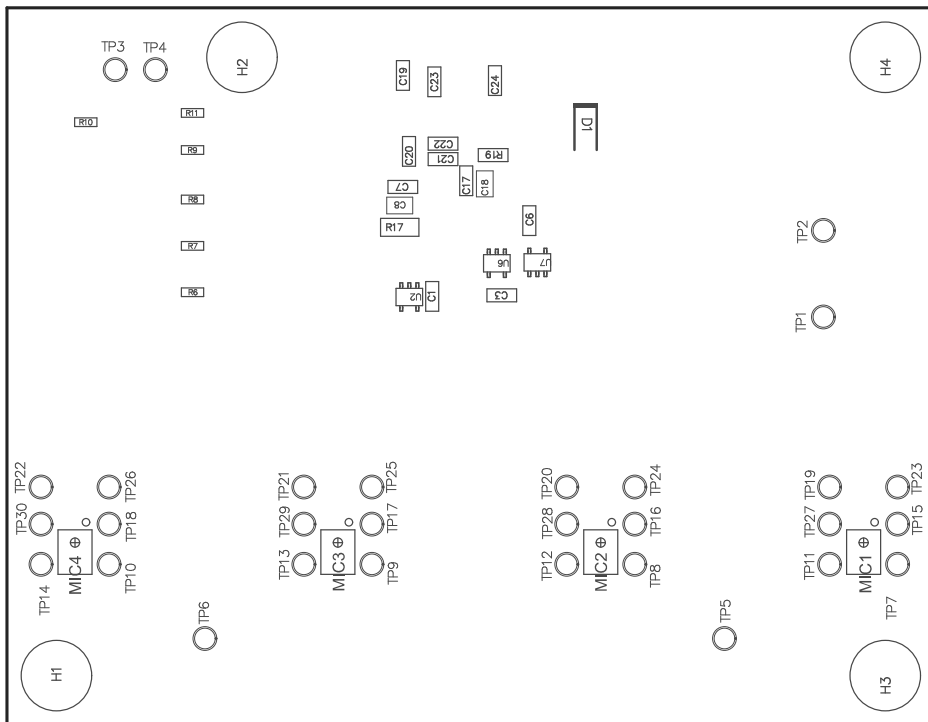


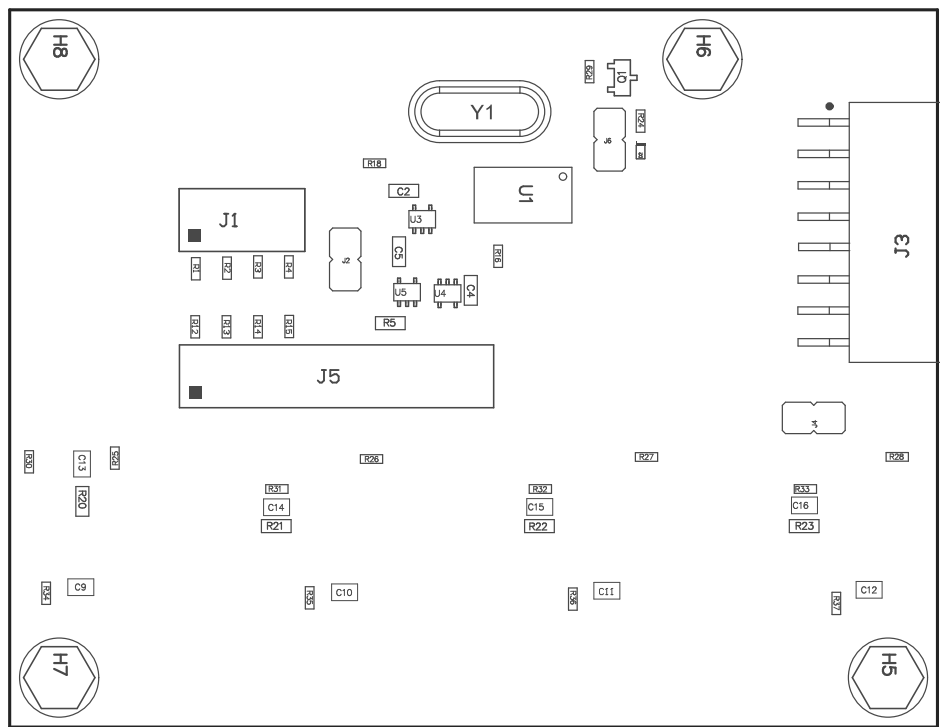
Z21 ■These assemblies are ESD sensitive, ESD precautions shall be observed.

Z22 ■These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z23 ■These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-01470	REV: A	SVN REV: Not In VersionControl
PLOT NAME = Top Assembly Drawing	GENERATED : 5/12/2017 10:52:07 AM	TEXAS INSTRUMENTS	



PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01470	REV: A	SVN REV: Not In VersionControl
PLOT NAME = Bottom Assembly Drawing	GENERATED : 5/12/2017	10:52:08 AM	TEXAS INSTRUMENTS

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